SPECIFICATION FOR APPROVAL

		CN:0
CUSTOMER	:	
PRODUCT TYPE	: -	SMD GLASS SEALING XTAL 8.0 × 4.5
NOMINAL FREQ.	: -	4.00000MHz
TXC P/N	: -	A204000008
REVISION	: -	A1
CUSTOMER P/N	:	
PM / SALES	: -	
DATE	:	
CUSTOMER SIGNA	TUR	RE & Date
	_	
	_	

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

MSL:Level 1
RoHS Compliant

Pb used in sealing glass material is exempt from EU directive



www.txccorp.com

PRODUCT SPECIFICATION SHEET

PRODUCT TYPE : SMD GLASS SEALING XTAL 8.0 x 4.5

NOMINAL FREQ. : 4.000000MHz

TXC P/N : A204000008

REVISION : A1

PE/RD	QA	MFG
Wen yuan Chang Wen yuan Chang	Zhong Lin Wu Zhong Lin Wu	zhi Jun Wu Zhi jun Wu
29-Ғеб-20	29-Гев-20	29-Гев-20

NOTE:

(1)The green product standard set by TXC is based upon the international standards. Related information is publicly described on the TXC's Website, and updated regularly. The document is compliant with the latest green product quality system directives at the time.

(2) Revision "Sx" is for engineering samples only. PE/RD's approval required.

(3)Revision "Ax" is production ready. PE, QA and MFG's approval required

MSL:Level 1
RoHS Compliant

Pb used in sealing glass material is exempt from EU directive



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Rev	Revise page	Revise contents	<u>Date</u>	Ref.No.	Reviser
S1	N/A	Initial released	16-Dec-19	N/A	Xiaohua Zhang
A1	N/A	S Turn A	29-Feb-20	N/A	Xiaohua Zhang



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Spec Sheet Contents

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■ ELECTRICAL SPECIFICATIONS

	Parameters	SYM.	Electrical Spec.				Notes	
	Parameters	STIVI.	MIN	TYP	MAX	UNITS	Notes	
1	Nominal Frequency	FL		4.000000)	MHz	-	
2	Oscillation Mode	-	Fı	undamen	tal	-	-	
3	Load Capacitance	CL		20		pF	-	
4	Frequency Tolerance	-		±20		ppm	at 25 ± 3 ℃	
5	Frequency Stability	-		±30		ppm	Over Operating Temp. Range (Reference 25° C)	
6	Operating Temperature	-	-40	~	85	$^{\circ}\!\mathbb{C}$	-	
7	Aging	-		±3		ppm	1st Year at 25 ± 3 ℃	
8	Drive Level	DL	-	50	100	uW	-	
9	Equivalent Resistance Rr	Rr	-	-	150	Ω	-	
10	Shunt Capacitance C0	C0	-	-	5	pF	-	
11	Insulation Resistance	-	500	-	-	МΩ	at DC 100V	
12	Storage Temperature Range	-	-40	~	85	$^{\circ}\!\mathbb{C}$	-	

Measure equipment

Electrical characteristics measured by S&A250B or equivalent.

Unit Weight:

0.185±0.008 g/pcs Reference

■ Attention (注意事項):

- 1. If you intend to use product on controls relating to medical equipment, aeronautical equipment, aerospace, military science, space equipment, etc.) please do not fail to advise us of your intention beforehand. 請勿將本產品使用在醫療,航空,宇航,軍事或與生命安全性相關的設備中,若需使用在上述應用請事前與TXC聯繫。
- 2. Crystal units will be damaged by ultrasonic welding process due to resonance of crystal wafer itself.

 If ultrasonic welding used, TXC strongly recommend verifying damage by ultrasonic weld.

 本產品在超音波封合的過程中晶片可能會因共振受損,若有超音波封合需求,TXC強烈建議應給予適當的驗證。
- 3. Crystal units will be damaged by plastic molding process due to pressure. If plastic molding used, TXC strongly recommend use seam welding products instead.

本產品在熱塑封合的過程中結構可能會受到熱壓力而損壞,若有熱塑封合需求,請給以適當的驗證。

4. Due to the deformation during PCB assembly or separation, it may cause damage to the crystal product structrue. We suggested that the distance over 15mm between crystal position and PCB edge or screw hole. When the PCB area less than 5cm² or out-off-shape PCB, we recommended to choose the seam sealing type crystal.

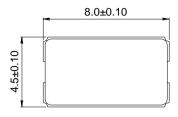
PCB因組裝或分切過程中的形變,可能對本產品結構造成損壞,建議本產品在PCB上的位置距離板邊或螺絲孔需大於15mm,當PCB最小面積小於5 cm²或PCB外型不規則時,建議選用金屬焊封的晶振產品。



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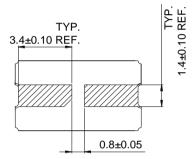
DIMENSIONS

(Unit:mm)

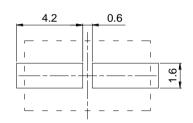






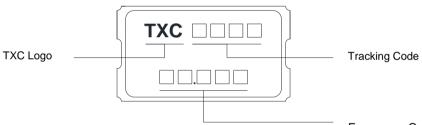


Suggested Layout



*Coplanarity of solderable areas Camber 0.10 mm Max

MARKING



Frequency Code

Ex.: 4.000000 MHz= 4.000

Date Code:

YEAR			MOI	NTH	JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	ОСТ	NOV	DEC
2005	2009	2013	2017	2021	Α	В	С	D	Е	F	G	Н	J	K	L	М
2006	2010	2014	2018	2022	N	Р	Q	R	S	Т	U	٧	W	Χ	Υ	Z
2007	2011	2015	2019	2023	а	b	С	d	е	f	g	h	j	k	ı	m
2008	2012	2016	2020	2024	n	р	q	r	S	t	u	٧	W	Х	У	Z

^{*}This date code will be cycled every four years

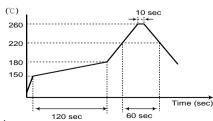
■ SUGGESTED REFLOW PROFILE

Production Location: China(Ningbo)

Solder melting point :220±10 $^{\circ}\text{C}$, 60 sec. Min.

Peak Temperature: 260 $\pm\,5~^{\circ}\!\!\mathrm{C}_{\,\cdot}$ 10 sec. Max.

Reflow passage time: twice



SUGGESTED MANUAL SOLDER CONDITION

Pressing a soliding iron of 350 °C on the terminal electrode for 4 seconds (twice).

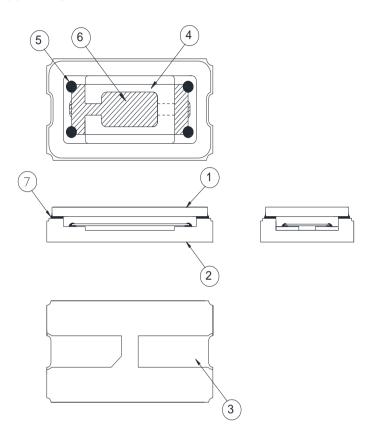
When using a soldering iron, press its tip on the part below the sealed part, avoiding glass-sealed part (otherwise, the glass will melt and air-tightness may be lost).

NOTE: After manual welding, the product should be placed at least 2 hours



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■ STRUCTURE ILLUSTRATION



NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Сар	Ceramic (Al ₂ O ₃)	-
2	Package	Ceramic (Al ₂ O ₃)	-
3	PAD	Au	Tungsten metalize
			+ Ni plating
			+ Au plating
4	Crystal blank	SiO ₂	-
5	Conductive adhesive	Resin+Ag	-
6	Electrode	Noble Metal	-
7	Sealing Glass	Glass (PbO)	-

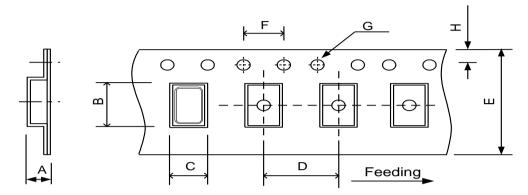
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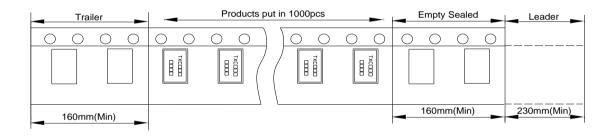
Α1

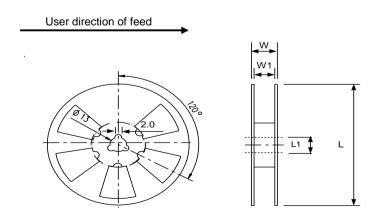
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■ EMBOSS CARRIER TAPE & REEL



DIMENSIONS	А	В	С	D	Е	F	G	Н	
DIMENSIONS	2.15±0.10	8.40±0.10	4.90±0.10	8.00±0.10	16.00±0.30	4.00±0.10	1.50±0.10	1.75±0.10	(UNIT: mm)





DIMENSIONS	L	L1	W	W1	pcs / Reel (UNIT : mm)
DIMENSIONS	180±1.00	13±0.50	20.5±0.20	16±0.10	Standard Reel Quantity is 1,000 pcs per reel

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■ PACKING

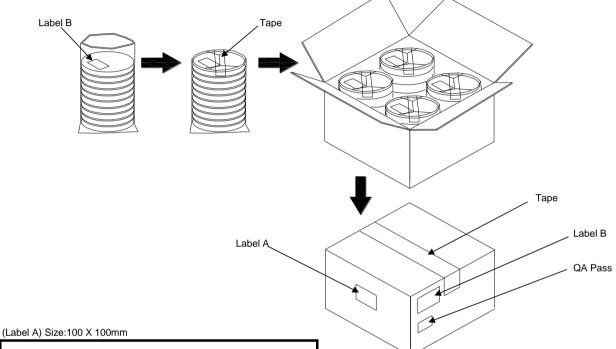
 Reel Quantity:
 Box Size:

 1. Reel X 5 (5 Reels x1)
 1. L200 X W200 X H140mm

 2. Reel X 10 (10 Reels x1)
 2. L200 X W200 X H250mm

 3. Reel X 20 (10 Reels x2)
 3. L400 X W200 X H250mm

 4. Reel X 40 (10 Reels x4)
 4. L400 X W400 X H280mm



TXC

Inv No: 00096815

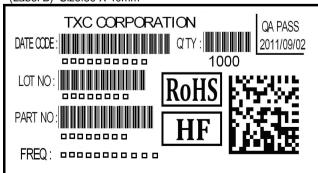
Po No: 21106326- 24- 1

Part No: DDDDDD

Q'ty: 40000 PCS

C/No: 157- 44

(Label B) Size:80 X 40mm



[STORAGE]

- 1.Don't be caught in the rain.
- 2.The storage environment shall be 5° C \sim 40°C temperature and 30% \sim 75%RH humidity and free from the sun shine.
- 3.If customers have special requirements, we can paste labels according to it.

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■ RELIABILITY SPECIFICATIONS (AEC-Q200 Compliant)

1.Mechanical Endurance

No.	Test Item	Test Metho	ods	Test Criteria
1.1	Mechanical Shock	2000 G , 0.3 m Sec. ,3 times for all 3	ВС	
		Frequency range	10 ~ 2000 Hz	
		Acceleration	20G	
1.2	Vibration	Amplitude	1.52mm	ВС
1.2	Vibration	Sweep time	20 minute	ВC
		Pendicular axes each test time 4 hours		
			(Total test time 12 hours)	
1.3	Terminal Strength	17.7N force for 60sec +/-1sec.		F
1.4	Board Flex	Duration time:60 Sec Minimum,Deviation	ВС	
		Temperature	245 °C +/- 5°C	
		Immersing depth	0.5 mm minimum	
1.5	Solderability	Immersion time	5 +/- 0.5 seconds	E
		Flux	Rosin resin methyl alcohol	
			solvent (1:4)	

2. Environmental Endurance

No.	Test Item	Test Methods	SPEC
2.1	Resistance To Soldering Heat	Test temperature 260 +/- 5 °C Test time 10 +/- 1 sec.	BCD
2.2	High Temp. Storage	+ 85°C ± 3 °C for 1000 ± 12 Hrs	BCD
2.3	Low Temp. Storage	- 55 °C ± 3 °C for 1000 ± 12 Hrs	BCD
2.4	Temperature cycle	-55°C ~85°C ,for 1000 cycles. 1 cycle 25 °C -55+/-3 °C 30 min. 2min Max.	BCD
2.5	Operational Life	1000 hrs @ 85± 3°C. Rated VDD applied with 1 MΩ.	BCD
2.6	High Temp & Humidity	85°C ± 3°C , RH 85% , 1000 Hrs	BCD



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RELIABILITY SPECIFICATIONS

Specifications	
Α	Frequency change: Within ±5ppm or in customer's specification.
В	Frequency change: Within ±10ppm or in customer's specification.
С	Equivalent series resistance(E.S.R) change: Within ±15% or 10Ω(larger value).
D	After conditioning, quartz crystal units shall be subjected to standard atmospheric conditions for 24 hour, and measured.
E	Minimum 95% of immersed terminal shall be covered with new uniform solder.
F	No damage on specimen

Measurement condition

Electrical characteristics measured by S&A250B or equivalent.